



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-04-19
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS30L45CT	H8DZ*F54Q02Y	A	9945	2018-04-19
Amount	UoM	Unit type	ST ECOPACK Grade	
1900	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
SIP	10-9.1-4.5	3	THROUGH HOLE
Comment	TO 220 AB NON ISOL		

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.61	Die - Leadframe	318
Lead	8.94	Soft solder	4703

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	H8D2*F54Q02Y					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	10.738	mg	supplier	die	Silicon (Si)	7440-21-3		10.099	mg	940492	5315
				supplier	metallization	Aluminium (Al)	7429-90-5		0.418	mg	38927	220
				supplier	metallization	Nickel (Ni)	7440-02-0		0.046	mg	4284	24
				supplier	metallization	Titanium (Ti)	7440-32-6		0.009	mg	837	5
				supplier	metallization	Tungsten (W)	7440-33-7		0.015	mg	1397	8
				supplier	Passivation	Silicon Oxide	7631-86-9		0.062	mg	5774	33
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.005	mg	466	3
				supplier	back side metallization	Gold (Au)	7440-57-5		0.015	mg	1397	8
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.069	mg	6426	36
Leadframe	M-004 Copper and its alloys	1253.534	mg	supplier	alloy	Copper (Cu)	7440-50-8		1251.375	mg	998278	658618
				supplier	alloy	Iron (Fe)	7439-89-6		1.253	mg	1000	659
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.376	mg	300	199
				supplier	metallization	Nickel (Ni)	7440-02-0		0.490	mg	390	258
				supplier	metallization	Phosphorus (P)	7723-14-0		0.040	mg	32	21
Soft solder	Solder	9.357	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	8.936	mg	955007	4703
				supplier	solder	Silver (Ag)	7440-22-4		0.234	mg	25008	123
				supplier	solder	Tin (Sn)	7440-31-5		0.187	mg	19985	98
Bonding wires	M-011 Other inorganic materials	10.589	mg	supplier	wire	Aluminium (Al)	7429-90-5		10.589	mg	1000000	5573
				supplier	wire	Aluminium (Al)	7429-90-5		10.589	mg	1000000	5573
Encapsulation	M-011 Other inorganic materials	609.420	mg	supplier	mold compound	Silica, vitreous	60676-86-0		530.195	mg	869999	279050
				supplier	mold compound	Epoxy resin	25068-38-6		60.942	mg	100000	32075
				supplier	mold compound	Phenol resin	29690-82-2		15.236	mg	25001	8019
				supplier	mold compound	Carbon Black	1333-86-4		3.047	mg	5000	1604
Connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348